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(12) **United States Design Patent**
Kanda

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(54) **SEMICONDUCTOR MODULE**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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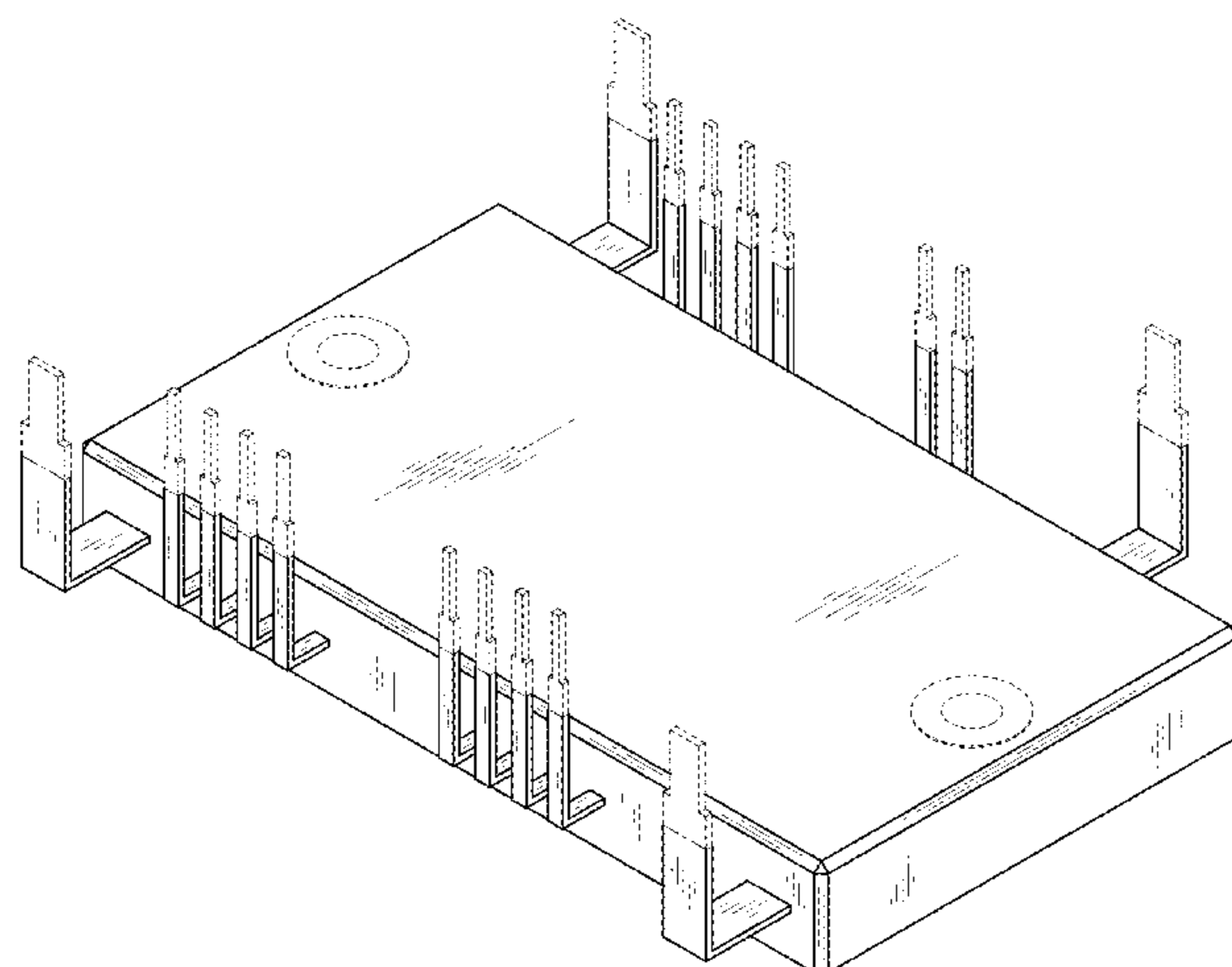
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(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182
CPC H01L 21/00; H01L 21/02433; H01L 2224/42; H01L 2224/43; H01L 2021/00; H01L 2021/02; H01L 2021/04; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/147; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/171151; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905; H01L 2224/08054; H05B 41/14; H02B 6/4201; G02B 6/4256; G02B 6/4257; G02B 6/4261; G02B 6/4262; G02B 6/42; G02B 6/4201; H05K 1/14; H05K 1/141; H05K 1/142; H05K 1/144; H05K 1/18; H05K 1/181; H05K 1/182; H05K

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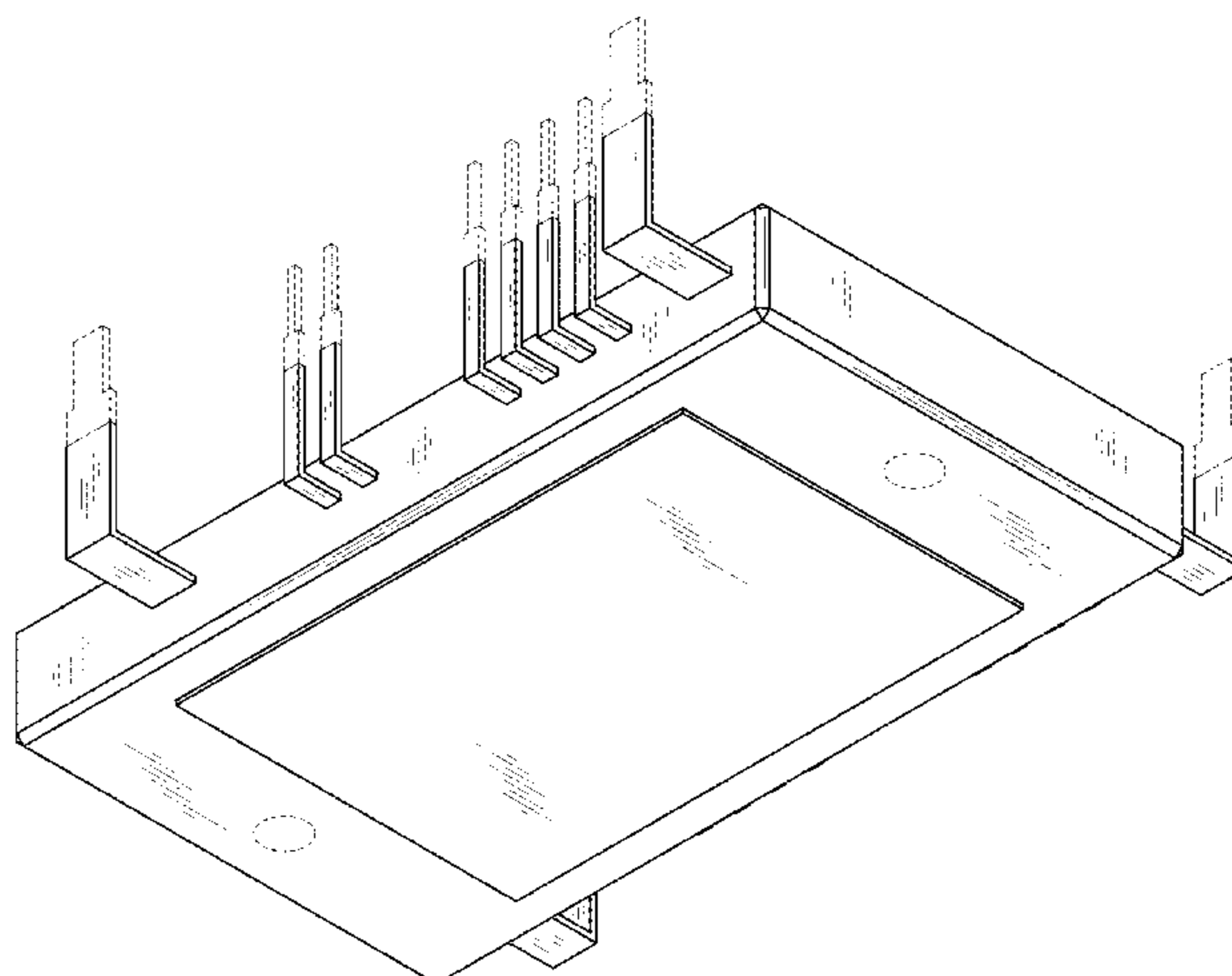
(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a semiconductor module showing our new design;
FIG. 2 is a rear, bottom, and left side perspective view thereof;
FIG. 3 is a front view thereof;
FIG. 4 is a rear view thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof;
FIG. 7 is a right side view, the left side view being identical to FIG. 7;
FIG. 8 is a cross-sectional view taken along line 8-8 in FIG. 5; and,
FIG. 9 is a cross-sectional view taken along line 9-9 in FIG. 5.

(Continued)



The even broken lines illustrate portions of the semiconductor module and form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design.

1 Claim, 9 Drawing Sheets

(58) **Field of Classification Search**

CPC .. 1/0228; H05K 1/0245; H05K 1/0236; H05K 1/0263

See application file for complete search history.

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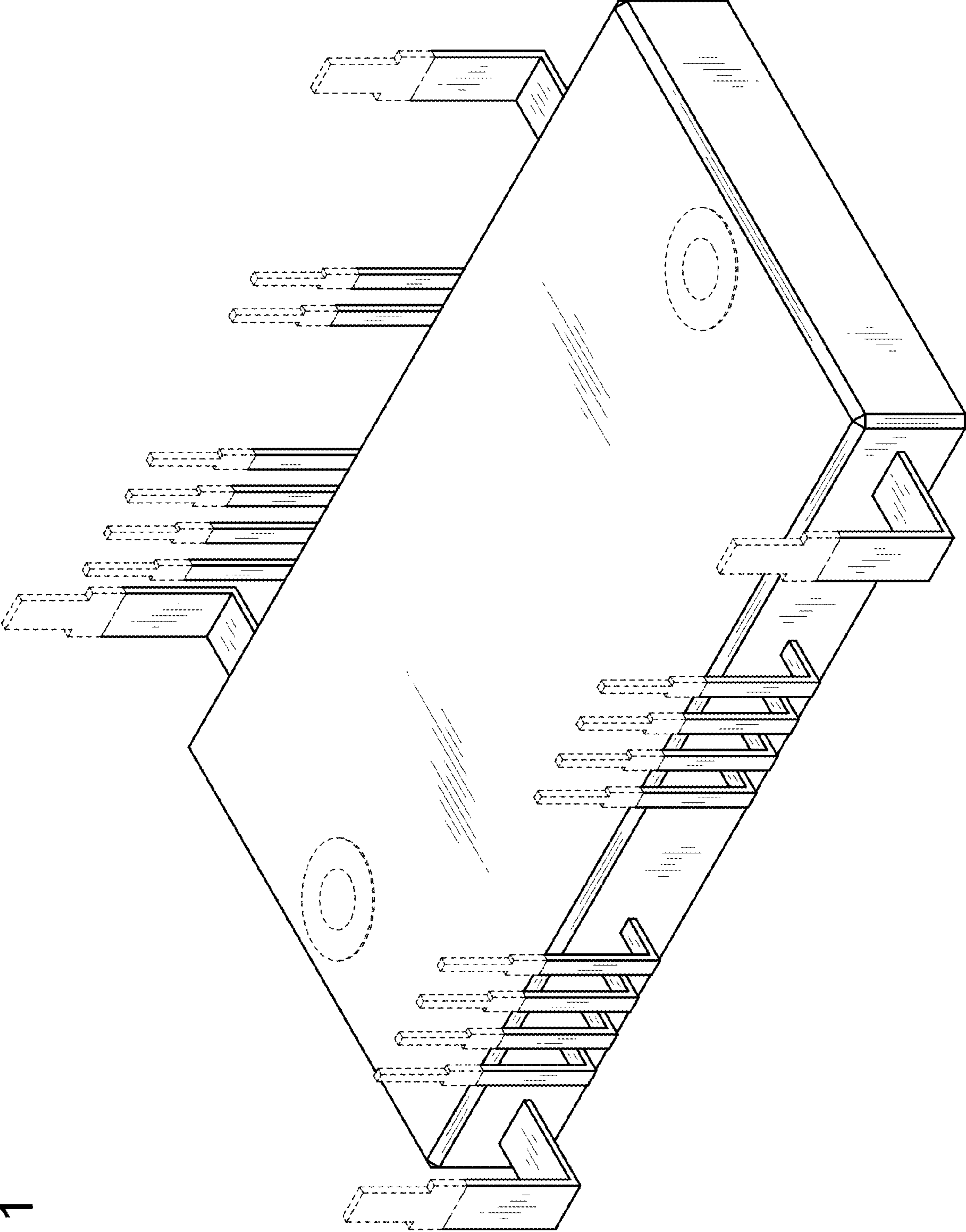


FIG. 1

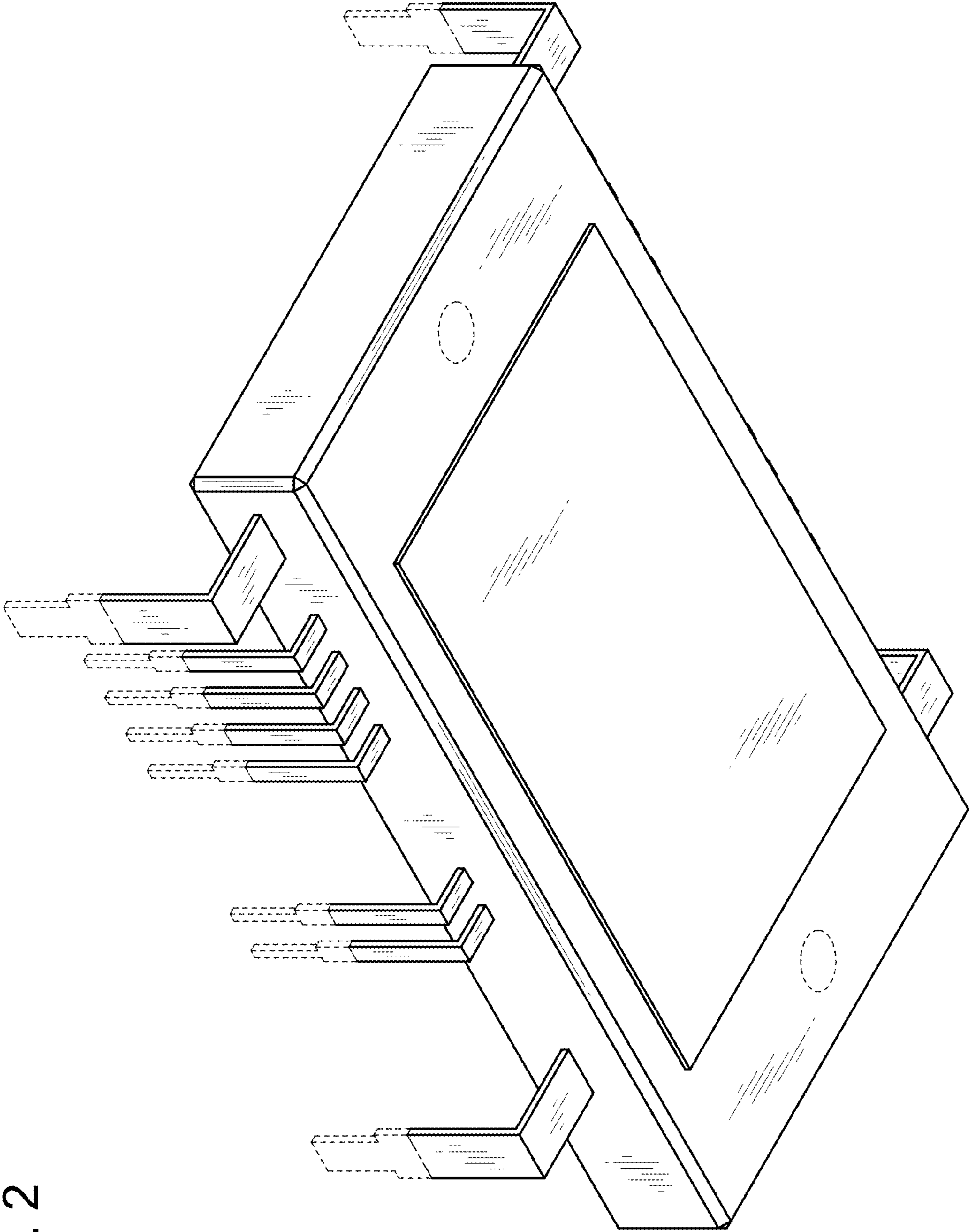


FIG. 2

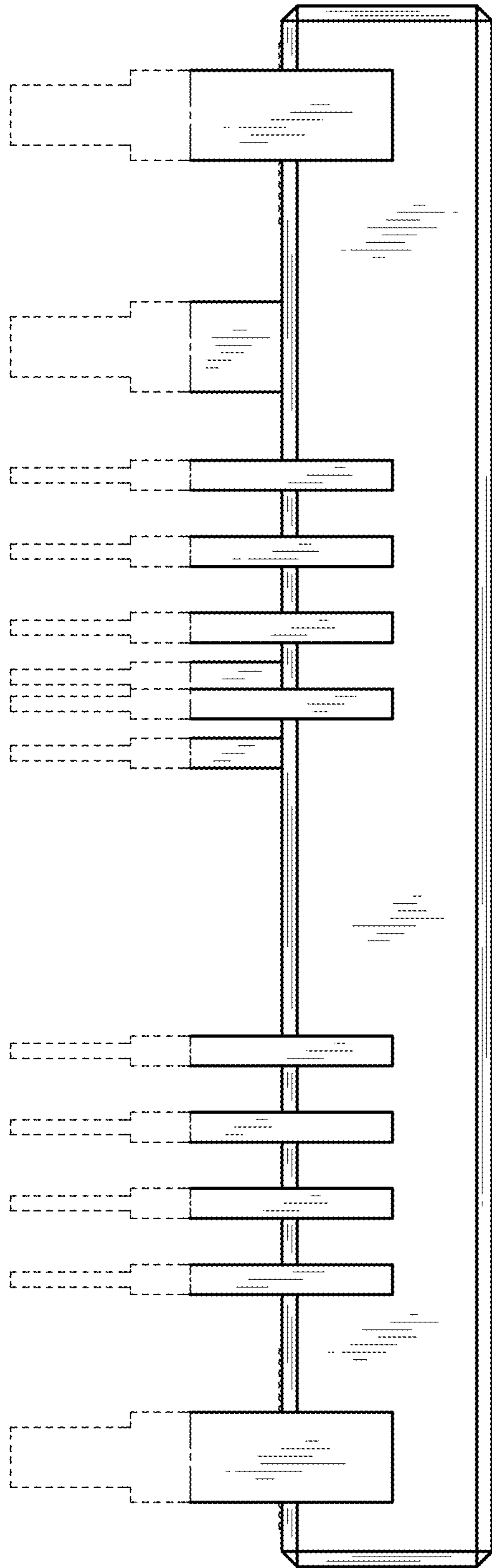


FIG. 3

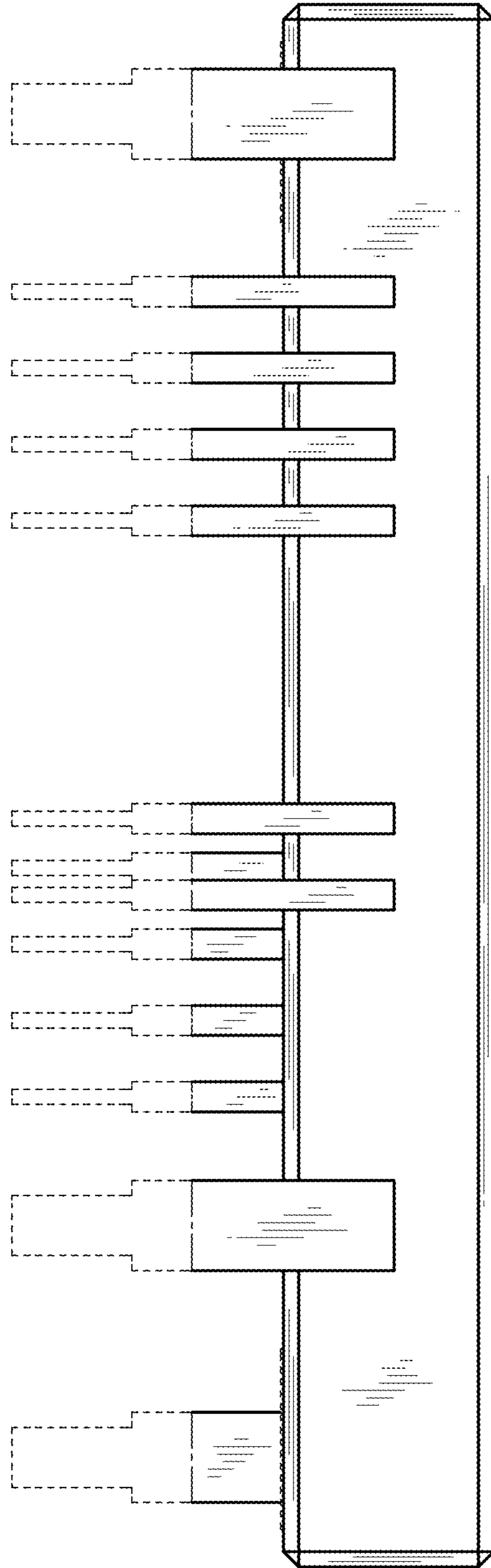


FIG. 4

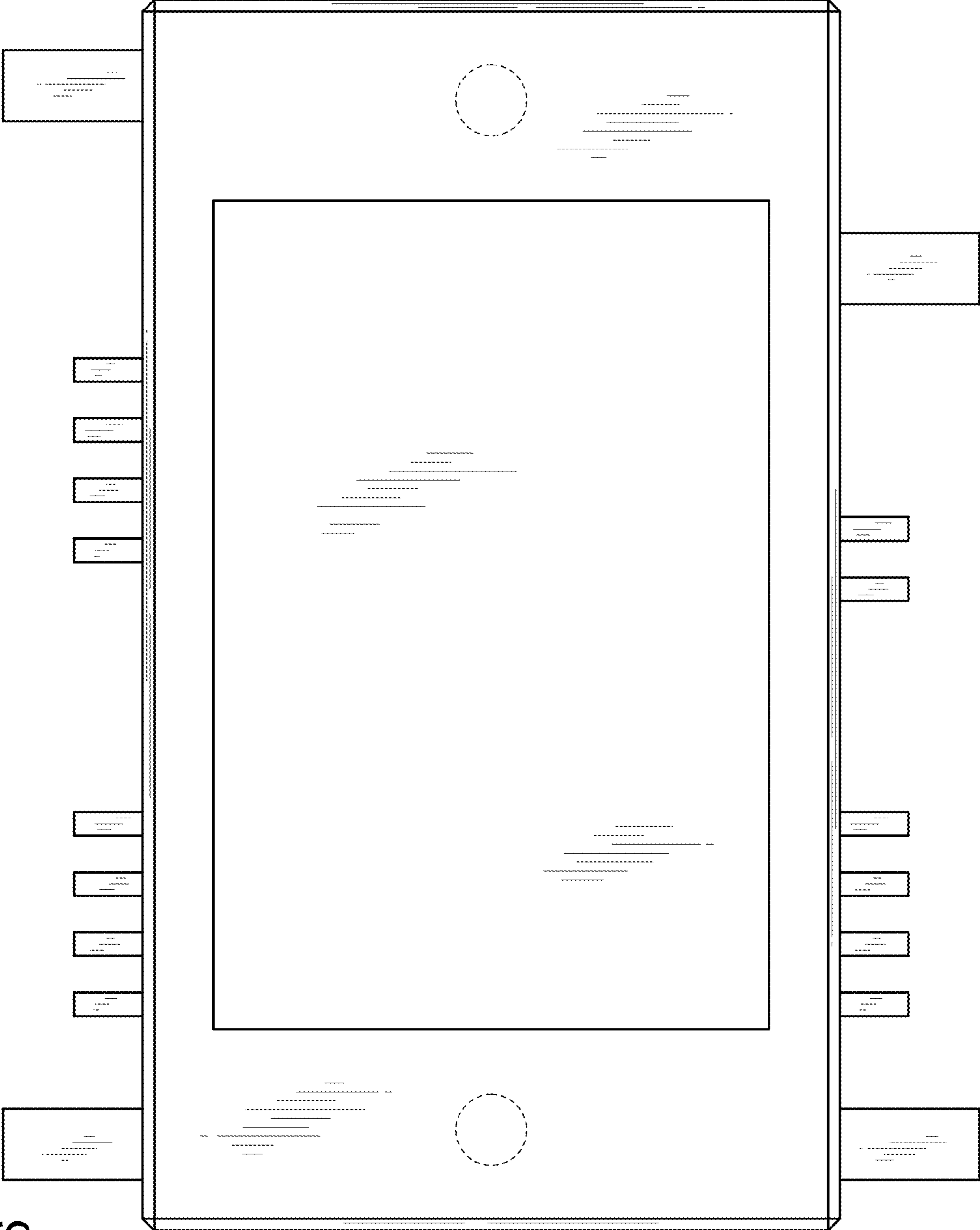


FIG. 6

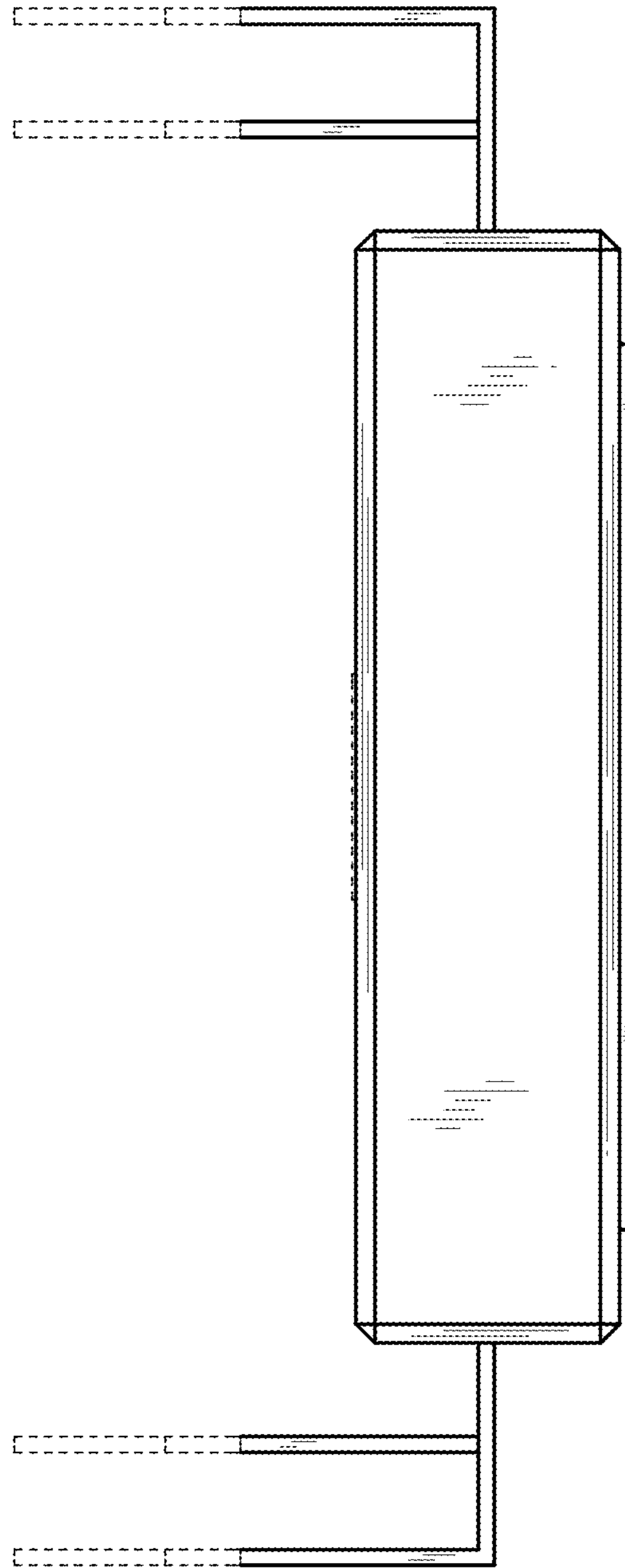


FIG. 7

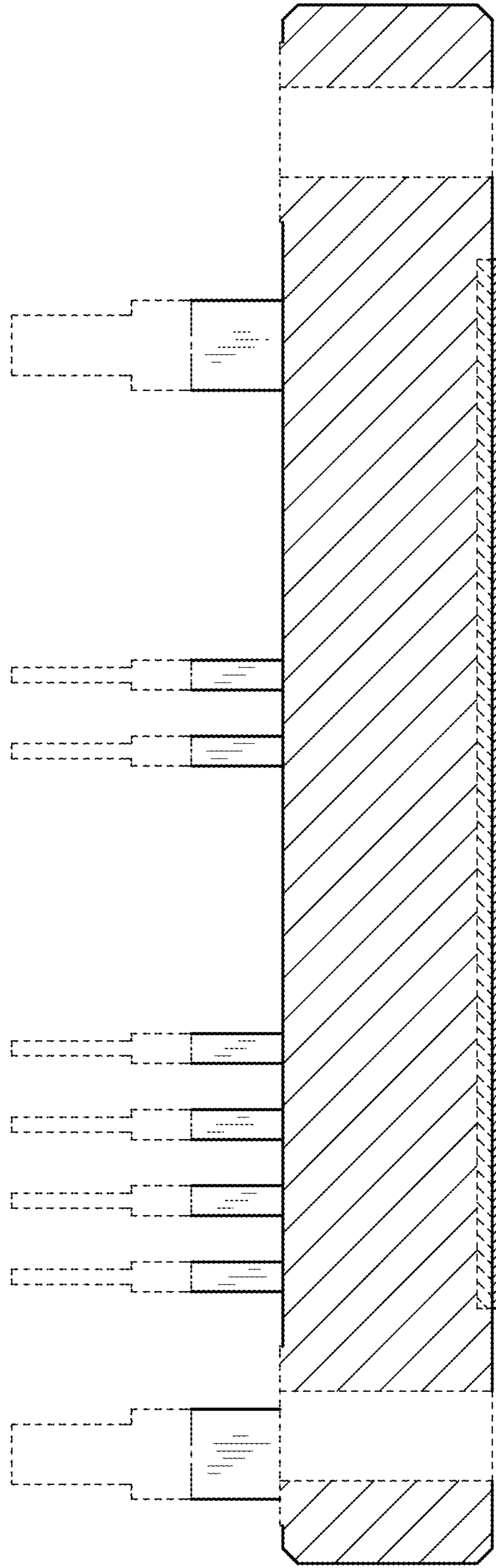


FIG. 8

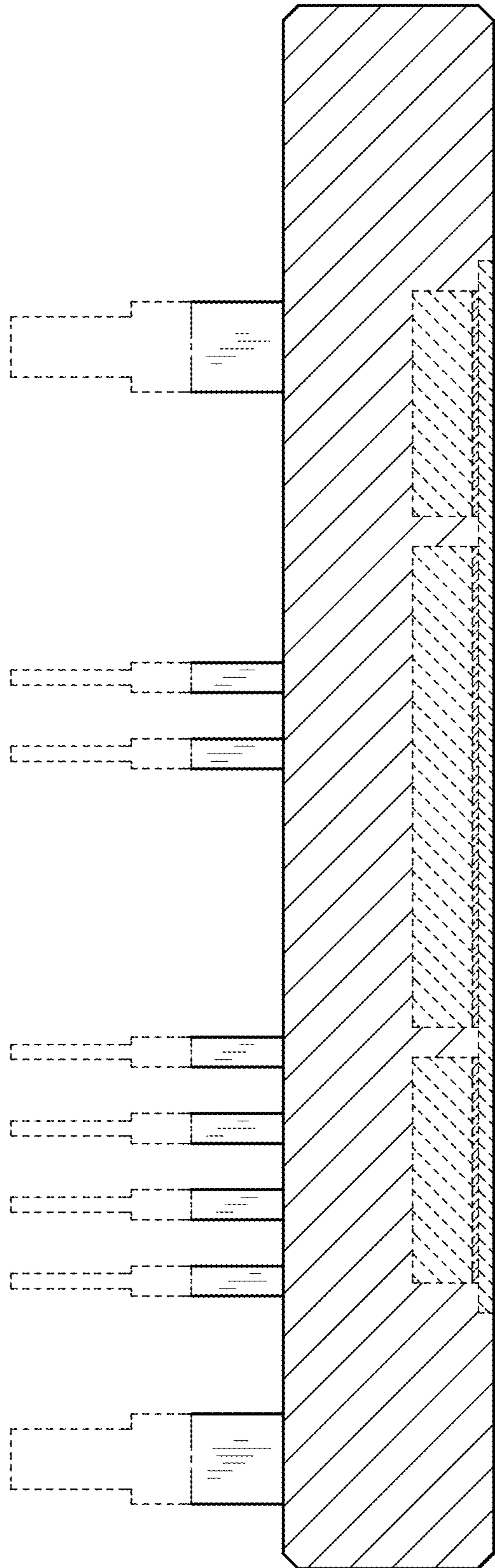


FIG. 9